

CLAIMS

1. An electroless copper plating solution, containing a water-soluble nitrogen-containing polymer in the electroless copper plating solution.
2. An electroless copper plating solution according to Claim 1, wherein the water-soluble nitrogen-containing polymer is a polyacrylamide or a polyethyleneimine.
3. An electroless copper plating solution according to Claim 1 or 2, wherein a weight average molecular weight (Mw) of the water-soluble nitrogen-containing polymer is at least 100,000, and Mw/Mn (Mn is a number average molecular weight thereof) is 10.0 or less.
4. The electroless copper plating solution according to any of Claims 1 to 3, wherein the electroless copper plating solution further contains glyoxylic acid and phosphinic acid as reducing agents.
5. An electroless copper plating method, performed using the electroless copper plating solution according to any of Claims 1 to 4.